



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



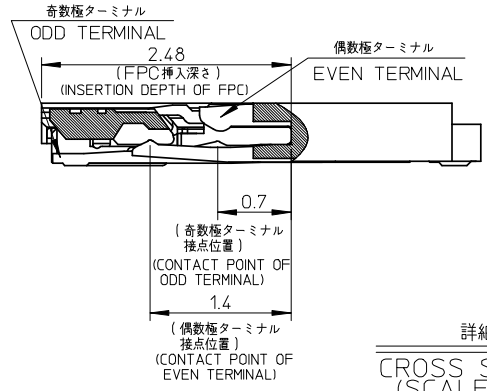
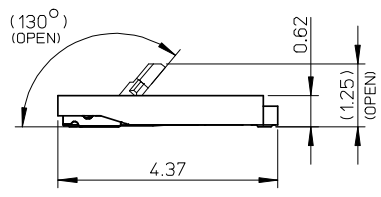
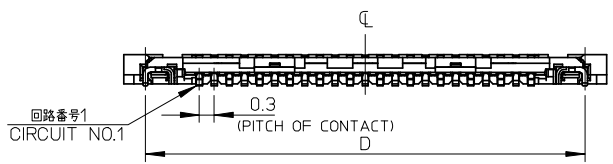
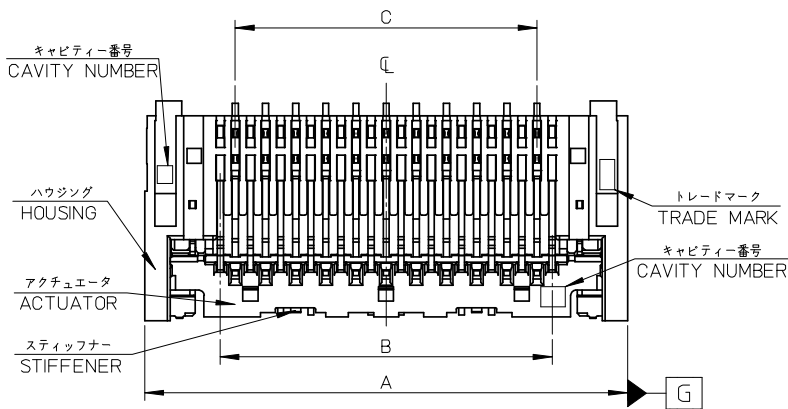
Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

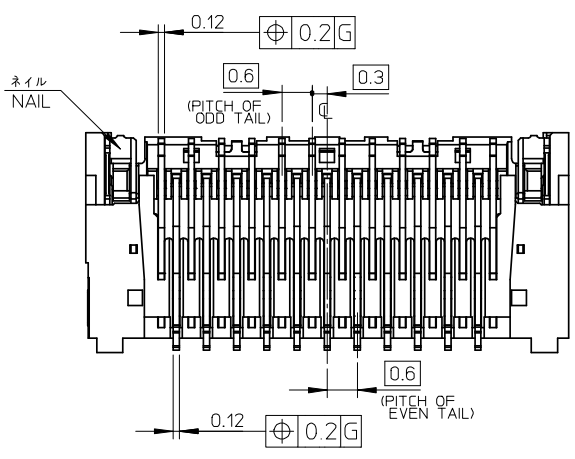
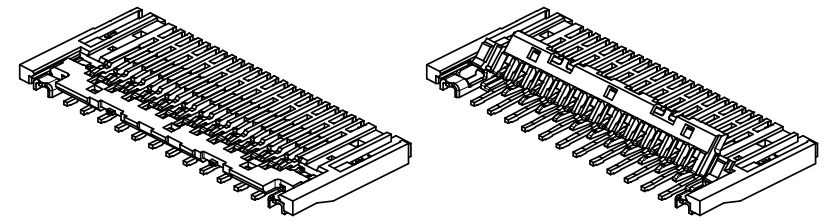
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





詳細図
CROSS SECTION
(SCALE 20:1)



| | | | | | | |
|-------|------|------|------|---------------------------------------|----------------------|----------------|
| 16.54 | 13.8 | 14.4 | 17.4 | 502761-4900 | 502761-4909 | 49 |
| 11.74 | 9 | 9.6 | 12.6 | 502761-3300 | 502761-3309 | 33 |
| D | C | B | A | オーダー番号 ORDER NO. (EMBOSSD TAPE) | 製品番号 MATERIAL NO. | 極数 CIRCUITS |

| | | | | | | | |
|---|--|--|----------------------------|--------------------|---|------------------------|---------------------------|
| REVISED EC NO: J2008-4277 DRWN: TRSUZUKI 2008/06/17 CHKD: KMORIKAWA 2008/06/18 APPR: KMORIKAWA 2008/06/18 | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | | SCALE 10:1 | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION |
| | 10 UNDER | ±0.2 | DRAWN BY TRSUZUKI | DATE 2008/06/17 | TITLE 0.3 FPC CONN (H=0.62) HSG ASSY BOTTOM CONTACT GOLD WITH NICKEL BARRIER | | |
| | 10 OVER 30 UNDER | ±0.25 | CHECKED BY KMORIKAWA | DATE 2008/06/17 | MOLEX INCORPORATED | | |
| | 30 OVER | ±0.3 | APPROVED BY HIRATA | DATE 2008/06/17 | DOCUMENT NO. SD-502761-001 | | |
| REV A | DESCRIPTION | ANGULAR ±1 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | MATERIAL NO. SEE CHART | | SHEET NO. 1 OF 3 | | |

注記 NOTES

1.使用材料 MATERIAL

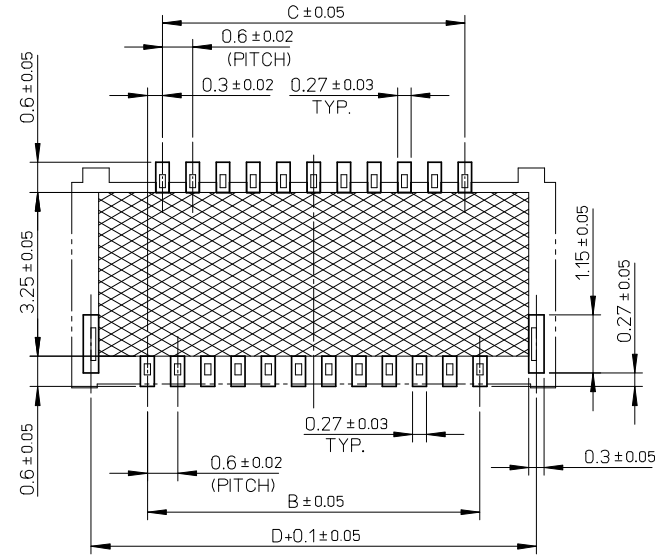
ハウジング : 液晶ポリマー ガラス充填 UL94V-0 (黒)
 HOUSING : LIQUID CRYSTAL POLYMER (GLASS FILLED)
 UL94V-0 (COLOR:BLACK)
 アクチュエータ : 液晶ポリマー ガラス充填 UL94V-0 (灰色)
 ACTUATOR : LIQUID CRYSTAL POLYMER (GLASS FILLED)
 UL94V-0 (COLOR:GRAY)
 ターミナル : 銅ニッケルスズ合金
 TERMINAL : COPPER NICKEL TIN ALLOY
 ネイル : リン青銅
 FITTING NAIL : PHOSPHOR-BRONZE
 スティッフナー : ステンレス鋼
 STIFFENER : STAINLESS STEEL

2.メッキ仕様 PLATING

ターミナル TERMINAL
 接点部 : 金メッキ
 CONTACT AREA : GOLD
 半田付け部 : 金メッキ
 SOLDER TAIL AREA : GOLD
 下地メッキ : ニッケルメッキ
 UNDER PLATING : NICKEL
 ネイル FITTING NAIL
 スズメッキ
 TIN
 下地メッキ : ニッケルメッキ
 UNDER PLATING : NICKEL

3.ソルダーテール半田付け面、及びネイル半田付け面の平坦度:0.15MAX.
 COPLANARITY OF SOLDER TAILS AND FITTING NAILS
 TO BE 0.15mm MAX.

4.ELV 及び RoHS適合品
 ELV AND RoHS COMPLIANT



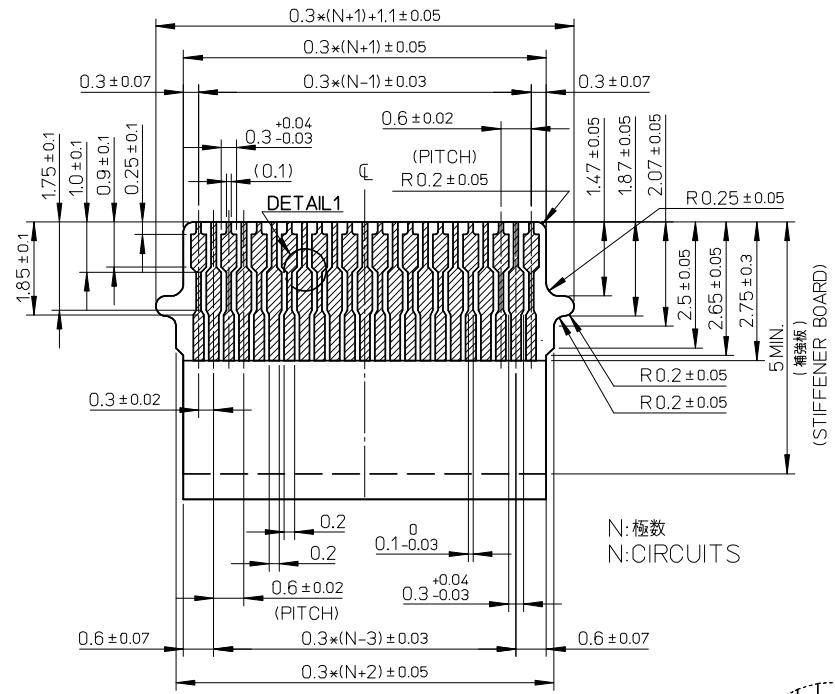
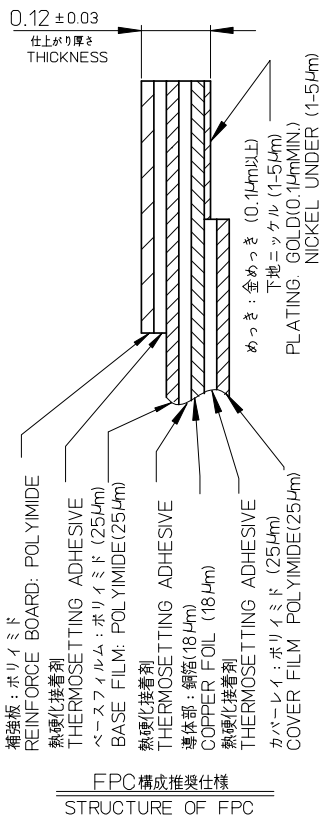
☒ : パターン及び半田禁止エリア
 : PATTERN AND SOLDER PROHIBITION AREA

推奨基板寸法

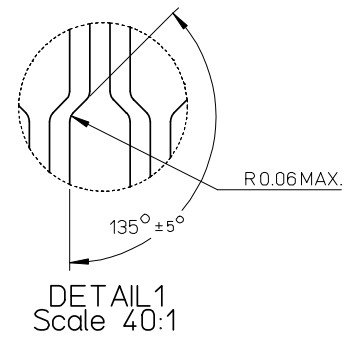
RECOMMENDED P.C.B. PATTERN LAYOUT

推奨メタルマスク仕様について:
 厚さ: 0.11mm、開口率: 弊社推奨パターンに対し60%
 ABOUT : METAL MASK SPECIFICATION
 RECOMMENDED THICKNESS : 0.11mm
 THE RECOMMENDED APERTURE RATE SHALL BE 60%
 USING OUR RECOMMENDED P.C.B. PATTERN LAYOUT.

| | | | | | | | | | |
|--|-------------|--|-------|-----------------------------|-------------------------------|---|------------------------|------------------------|--|
| SEE SHEET 1 EC NO.: J2008-4277 DRWN: TRSUZUKI 2008/06/17 CHKD: KMORIKAWA 2008/06/18 APPR: KMORIKAWA 2008/06/18 | DESCRIPTION | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | | SCALE 10:1 | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION | |
| | | 10 UNDER | ±0.2 | DRAWN BY TRSUZUKI | DATE 2008/06/17 | TITLE 0.3 FPC CONN (H=0.62) HSG ASSY BOTTOM CONTACT GOLD WITH NICKEL BARRIER | | | |
| | | 10 OVER 30 UNDER | ±0.25 | CHECKED BY KMORIKAWA | DATE 2008/06/17 | MOLEX INCORPORATED | | | |
| | | 30 OVER | ±0.3 | APPROVED BY HHRATA | DATE 2008/06/17 | | | | |
| ANGULAR | ±1 ° | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | MATERIAL NO. SEE SHEET 1 | DOCUMENT NO. SD-502761-001 | SHEET NO. 2 OF 3 | | | |



適合する金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD PLATING
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.12 ± 0.03)
(THICKNESS: 0.12 ± 0.03)



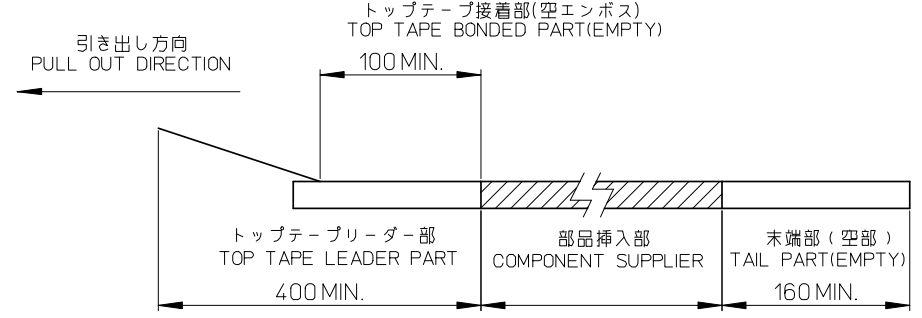
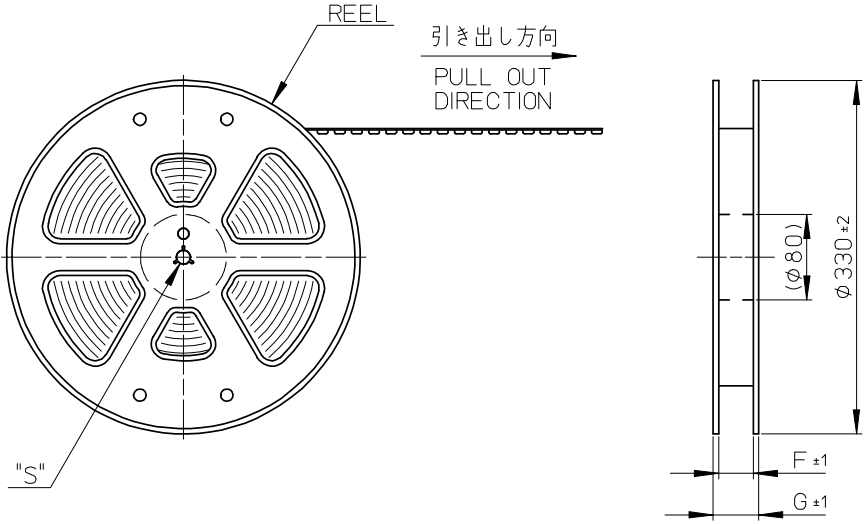
FPCについて:
抜き方向は、導体側から補強板側を推奨致します。
補強フィルム材質は、ポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、
染み出しが無い様、お願い致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFNER FILM SIDE.
RECOMMENDED MATERIAL:
STIFFENER FILM: POLYIMIDE
BONDING AGENT: THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND
BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE
CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

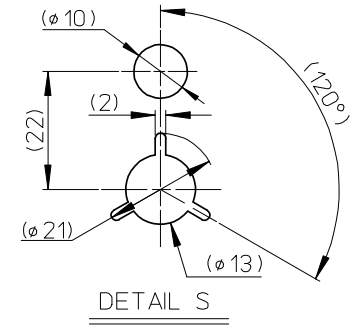
| | | | | | | | | | | |
|---|-------------------------|--|--------|-----------------------------|--------------------|---|------------------------|------------------------|--|--|
| SEE SHEET 1 EC NO: J2008-4277 DRWN: TRSUZUKI 2008/06/17 CHKD: KMORIKAWA 2008/06/18 APPR: KMORIKAWA 2008/06/18 | DESCRIPTION REV A | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | | SCALE 10:1 | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION | | |
| | | 10 UNDER | ± 0.2 | DRAWN BY TRSUZUKI | DATE 2008/06/17 | TITLE 0.3 FPC CONN (H=0.62) HSG ASSY BOTTOM CONTACT GOLD WITH NICKEL BARRIER | | | | |
| | | 10 OVER 30 UNDER | ± 0.25 | CHECKED BY KMORIKAWA | DATE 2008/06/17 | MOLEX INCORPORATED | | | | |
| | | 30 OVER | ± 0.3 | APPROVED BY HHRATA | DATE 2008/06/17 | | | | | |
| ANGULAR ± 1 ° | | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | MATERIAL NO. SEE SHEET 1 | | DOCUMENT NO. SD-502761-001 | | SHEET NO. 3 OF 3 | | |
| THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | | | | | | | |

NOTES

1. 製品詳細寸法につきましては、SD-502761-001 を参照ください。
RE DETAILED DIMENSION, SEE SD-502761-001
2. 梱包数量：3000個/リール
NUMBER OF CONNECTORS：3000PCS/REEL
3. リードテープの長さ
LEAD TAPE LENGTH

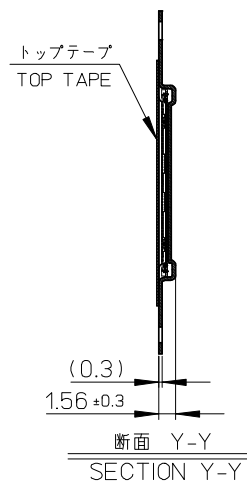
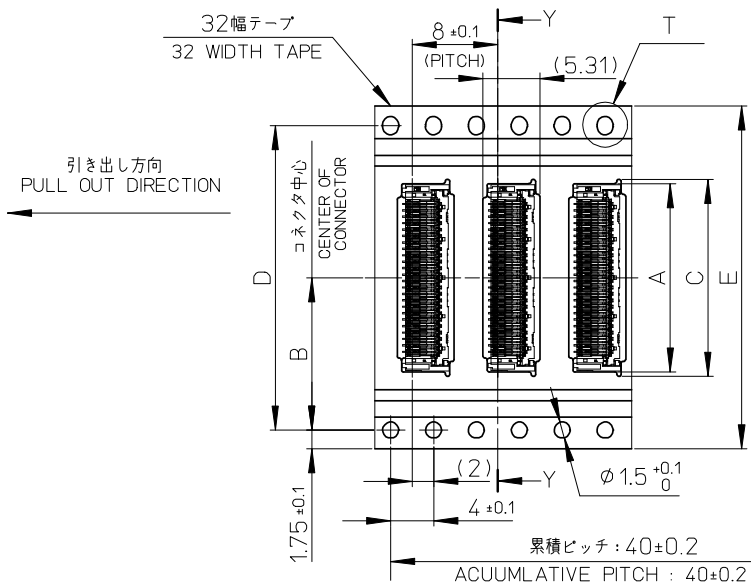


4. 材料(MATERIAL)
 キャリアテープ(CARRIER TAPE)：ポリスチレン(POLYSTYRENE)
 トップテープ(TOP TAPE)：PET, PE, PEF
 リール(REEL)：ポリスチレン(POLYSTYRENE) <リサイクル材を含む>
 <RECYCLE MATERIAL CONTAINED>
5. ELV 及び RoHS適合品
 ELV AND RoHS COMPLIANT.

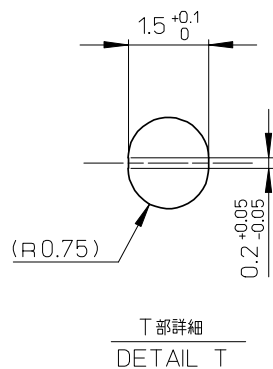
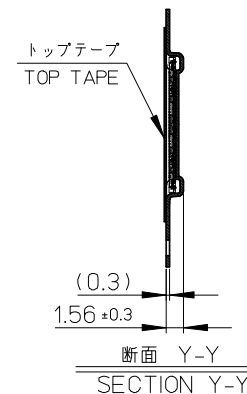
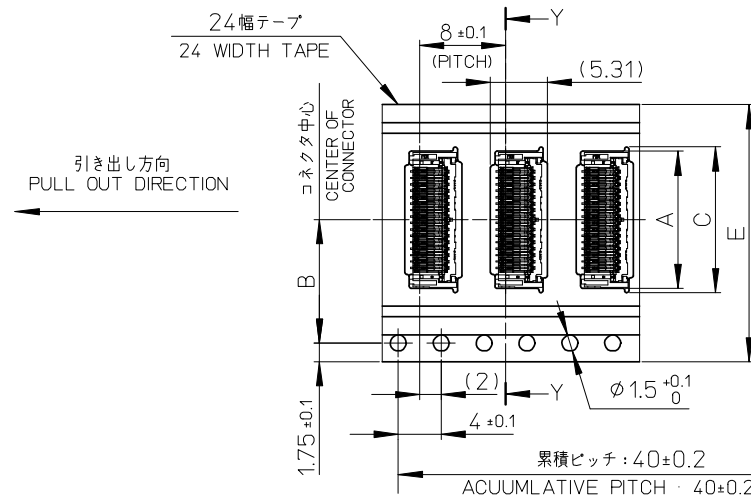


| | | | | | | | | |
|---|---|-------------|----------------------------|---------------|--|------------------------|------------------------|--|
| RELEASED EC NO: J2008-3700 DRWN: TRSUZUKI 2008/06/13 CH'KD: KMORIKAWA 2008/06/13 APPR: KMORIKAWA 2008/06/16 | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | | SCALE --- | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION | |
| | 10 UNDER | ± 0.2 | DRAWN BY | DATE | TITLE | | | |
| | 10 OVER 30 UNDER | ± 0.25 | TRSUZUKI | 2008/06/11 | 0.3 FPC CONN (H=0.62) EMBOSSED TAPE PACKAGE GOLD WITH NICKEL BARRIER | | | |
| | 30 OVER | ± 0.3 | CHECKED BY | DATE | | | | |
| | ANGULAR $\pm 1^\circ$ | | APPROVED BY | DATE | molex MOLEX INCORPORATED | | SHEET NO. | |
| | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | HHIRATA | 2008/06/11 | DOCUMENT NO. | | 1 OF 2 | |
| | | SEE SHEET 2 | | SD-502761-002 | | | | |
| 0 | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | | | | |

キャリアテープ幅: 32mm品



キャリアテープ幅: 24mm品



| | | | | | | | | |
|------|------|-------------------------------------|------|------|------|------|----------------------|----------------|
| 37.4 | 33.4 | 32±0.3 | 28.4 | 18.4 | 14.2 | 17.6 | 502761-4900 | 49 |
| 29.4 | 25.4 | 24±0.3 | --- | 13.6 | 11.5 | 12.8 | 502761-3300 | 33 |
| G | F | E キャリアテープ幅 CARRIER TAPE WIDTH | D | (C) | (B) | (A) | 製品番号 MATERIAL NO. | 極数 CIRCUITS |

| | | | | | | | | |
|---|--|-------|---|--|---|------------------------|------------------------|--|
| SEE SHEET 1 EC NO: J2008-3700 DRWN: TRSUZUKI 2008/06/13 CHKD: KMORIKAWA 2008/06/13 APPR: KMORIKAWA 2008/06/16 | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | | SCALE --- | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION | |
| | 10 UNDER | ±0.2 | DRAWN BY DATE TRSUZUKI 2008/06/11 | | TITLE 0.3 FPC CONN (H=0.62) EMBOSSED TAPE PACKAGE GOLD WITH NICKEL BARRIER | | | |
| | 10 OVER 30 UNDER | ±0.25 | CHECKED BY DATE KMORIKAWA 2008/06/11 | | | | | |
| | 30 OVER | ±0.3 | APPROVED BY DATE HIRATA 2008/06/11 | | MOLEX INCORPORATED | | | |
| | ANGULAR | ±1 ° | MATERIAL NO. SEE CHART | | DOCUMENT NO. SD-502761-002 | | SHEET NO. 2 OF 2 | |
| 0 | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | SIZE A3 | | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | |